

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Eun Jong LEE</td> <td>11/17/2011</td> </tr> <tr> <td>Youngsoo YUK</td> <td>11/17/2011</td> </tr> <tr> <td>Yongho KIM</td> <td>11/23/2011</td> </tr> <tr> <td>Kiseon RYU</td> <td>11/08/2011</td> </tr> </tbody> </table>		Name	Execution Date	Eun Jong LEE	11/17/2011	Youngsoo YUK	11/17/2011	Yongho KIM	11/23/2011	Kiseon RYU	11/08/2011
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Eun Jong LEE	11/17/2011										
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RECEIVING PARTY DATA											
Name:	LG Electronics Inc.										
Street Address:	20 Yeouido-dong, Yeongdeungpo-gu										
City:	Seoul										
State/Country:	REPUBLIC OF KOREA										
Postal Code:	150-721										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13320745</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13320745						
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CORRESPONDENCE DATA											
Fax Number:	(213)623-2211										
Phone:	213-623-2221										
Email:	patent@lhlaw.com										
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>											
Correspondent Name:	LEE, HONG, DEGERMAN, KANG & WAIMEY										
Address Line 1:	660 S. FIGUEROA STREET										
Address Line 2:	Suite 2300										
Address Line 4:	LOS ANGELES, CALIFORNIA 90017										
ATTORNEY DOCKET NUMBER:	2101-5147										
NAME OF SUBMITTER:	Harry S. Lee										

OP \$40.00 13320745

Total Attachments: 4

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ASSIGNMENT

(1-8) *Insert Name(s) of Inventor(s)* (1) LEE, Eun Jong (4) RYU, Kiseon
(2) YUK, Youngsoo (6)
(3) KIM, Yongho (7)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(9) *Insert name of Assignee* (9) **LG ELECTRONICS INC.**
(10) *Insert state of Incorporation of Assignee* (10) **Korea**
(11) *Insert address of Assignee* (11) 20 Yeouido-dong, Yeongdeungpo-gu, Seoul, 150-721, Korea

(12) *Insert identification of Invention, such as Title, Case Number or Foreign Application Number* (hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as
(12) STRUCTURE OF EFFICIENT SIGNALING HEADER IN BROADBAND WIRELESS ACCESS SYSTEM
for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.
(13) *Insert Date of Signing of Application* (13)

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

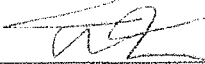
2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

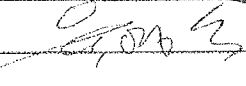
3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

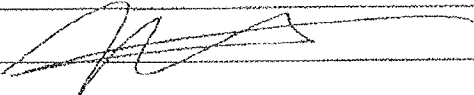
5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby appoints **the Attorneys associated with Customer No. 035884** the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: Nov. 17, 2011 Signature of Inventor: 

Date: Nov. 17, 2011 Signature of Inventor: 

Date: _____ Signature of Inventor: _____

Date: Nov. 8, 2011 Signature of Inventor: 

ASSIGNMENT

(1-8) <i>Insert Name(s) of Inventor(s)</i>	(1) LEE, Eun Jong	(4) RYU, Kiseon
	(2) YUK, Youngsoo	(6)
	(3) KIM, Yongho	(7)

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Date: 2011. Nov. 23 Signature of Inventor 

Date: _____ Signature of Inventor _____